

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Satya et al.

Attorney Docket No.: KLAIP016F/

Application No.: 09/648,095

Examiner: P. Cao

Filed: August 25, 2000

Group: 2811

Title: CHEMICAL MECHANICAL POLISHING

TEST STRUCTURES AND METHODS

FOR INSPECTING THE SAME

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail to: Commissioner of Patents and Trademarks, Washington, DC 20231 on January 26, 2002.

Signed:

Natalie Morgan

AMENDMENT A

Commissioner for Patents Washington, D.C. 20231

Dear Sir:

It is respectfully submitted that the Examiner enters the following amendments in response to the Office Action dated 6 November 2002, a response to which is due on 6 February 2003.

In the Claims:

Please substitute the following clean claims 7, 54, and 58 for any previous corresponding claims. Additionally, please add the following new claim 107. A marked up version of the claims is presented in the attached Appendix.

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7. (Amended Once) A method of fabricating a semiconductor die, comprising: providing a semiconductor die having a plurality of first areas which are specified by a design as containing structures selected from a group consisting of a product structure and a test structure;